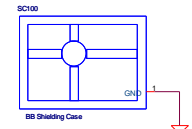
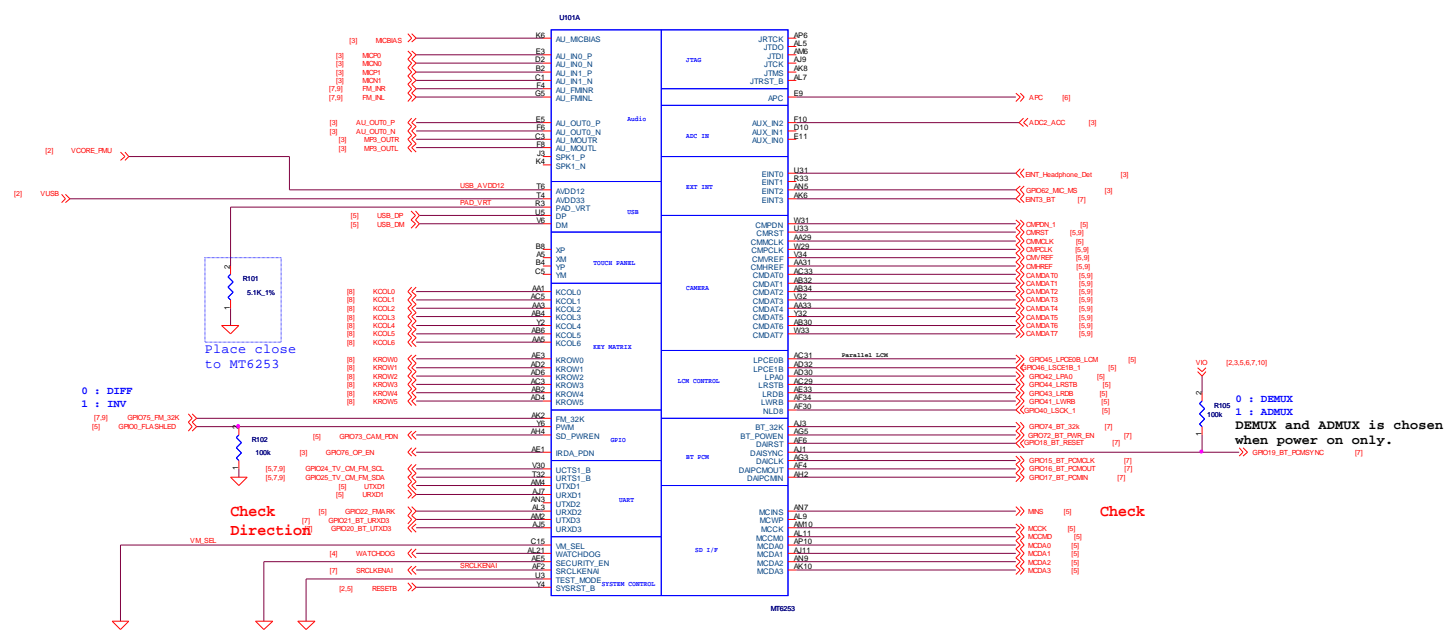


BASEBAND



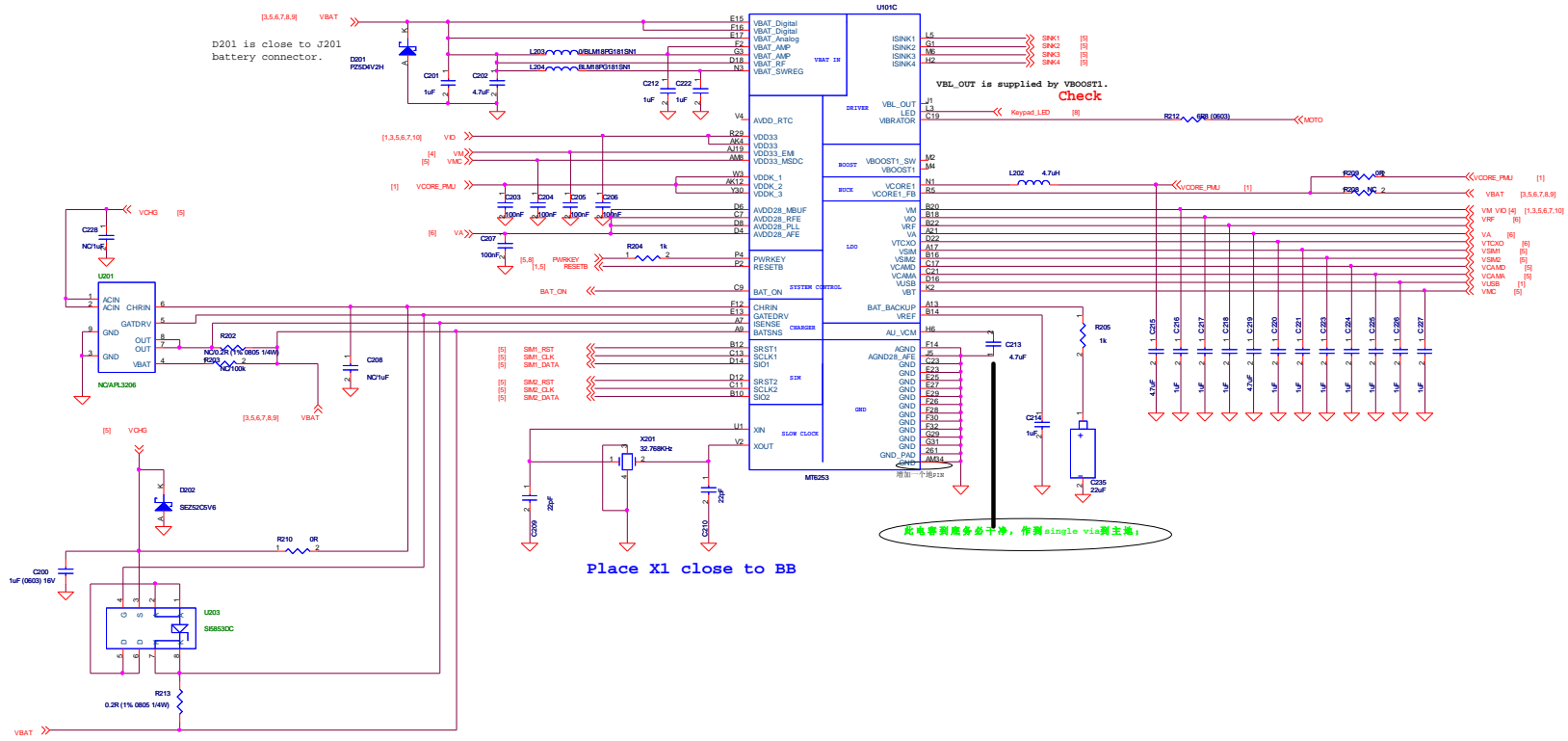
BASIC



The Application Note

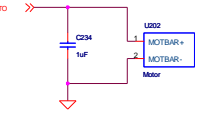
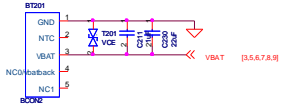
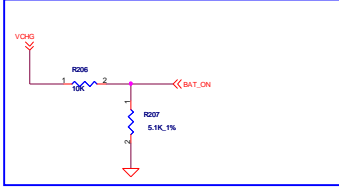
120_M0	File: A01/120A_P00
120_DATA	File: A01/0120D
120_C00	File: A01/0120C

BASEBAND-POWER



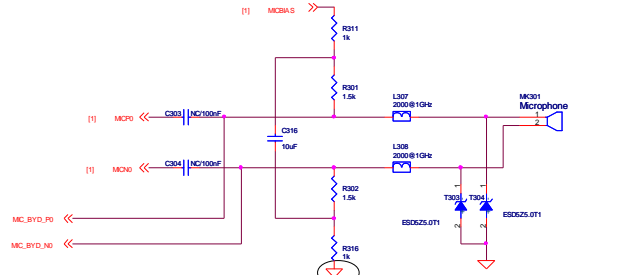
此电容到底是否必须，作到single via到主地。

Check, Trace 4mil is enough

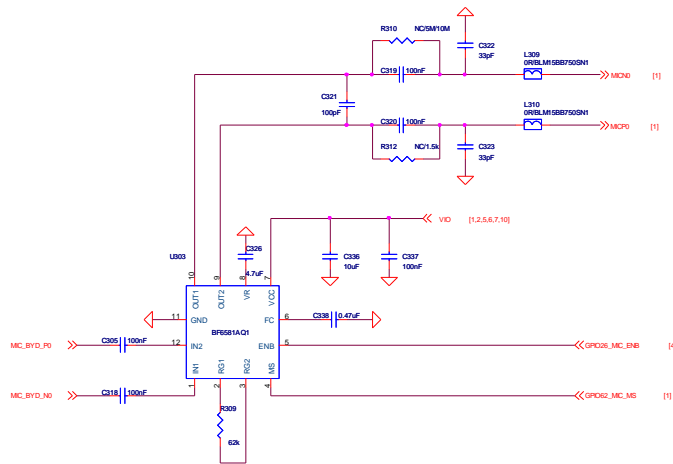


	Symbol	Vout (V)	Iout (mA)	Setting
Buck	VCORE	1.2	200	
RF LDO	VRF	2.8	200	
	VTCXO	2.8	20	
Analogue LDO	VA	2.8	125	
	VCM_A	1.5/1.8/2.5/2.8	150	
Digital LDO	VM	1.8/2.8	200	VM_SEL
	VIO	2.8	100	
	VSIM	1.8/3.0	100	
	VUSB	3.3	100	
	VBT	1.3/1.5/1.8/2.5/2.8/3.0/3.3	100	
	VCM_D	1.3/1.5/1.8/2.5/2.8/3.0/3.3	100	
	VIM2	1.3/1.5/1.8/2.5/2.8/3.0/3.3	100	
Vibrator	VIBR	1.8/3.0	200	
RTC	VBACKUP	2.8	2	
Boost Converter	VBOOST1	3.4-5.5	100	

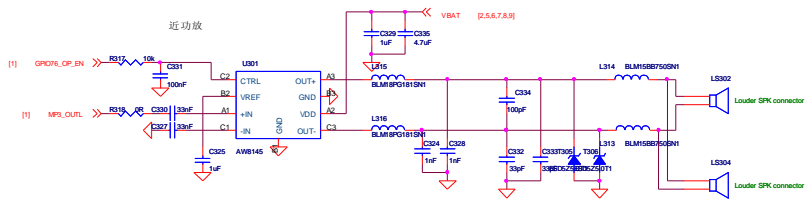
HANDSET MICPHONE



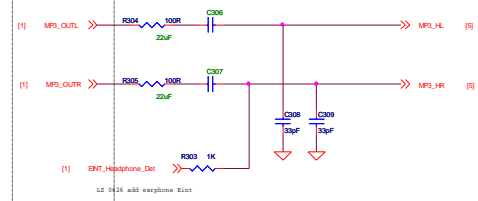
此GND务必单独过孔到主地，不和其它GND连接。



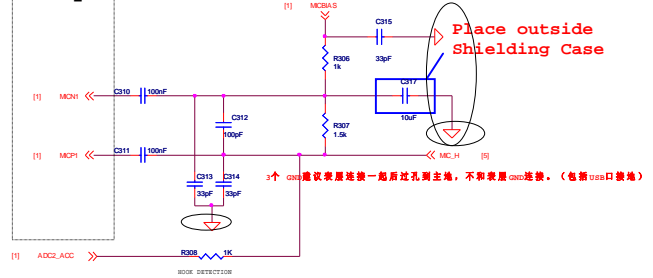
LoudSPK



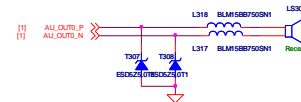
Earphone Receiver



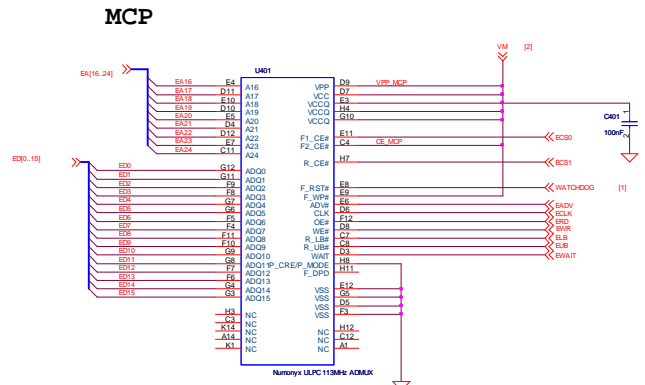
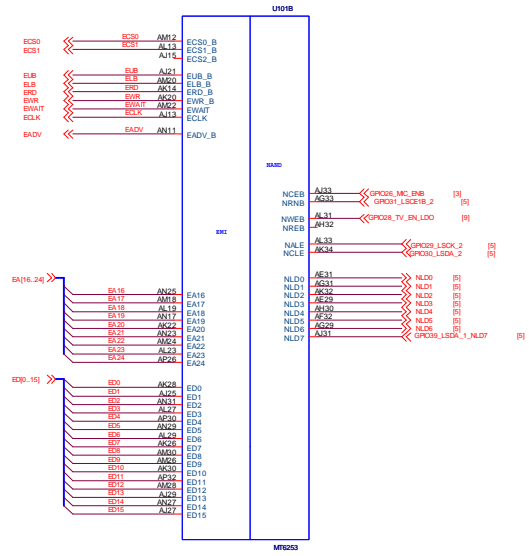
Earphone MICOPHONE

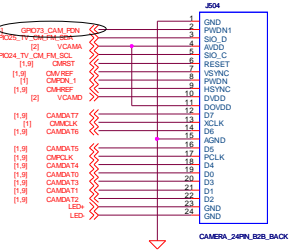
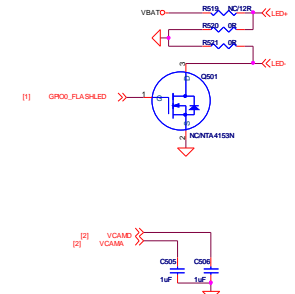
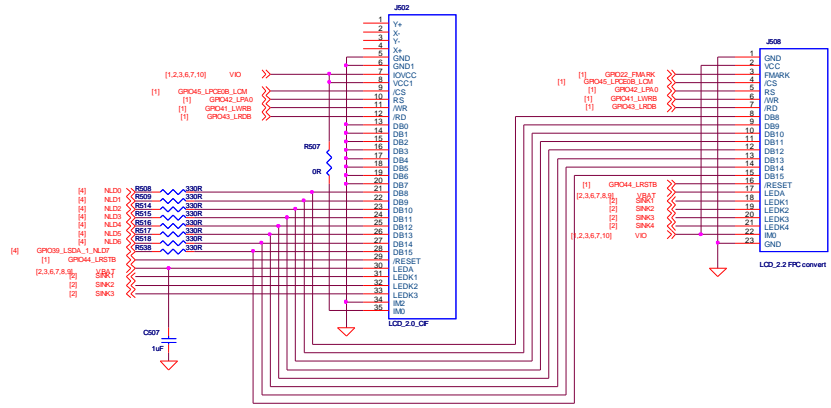


Detection of Send key on Earphone

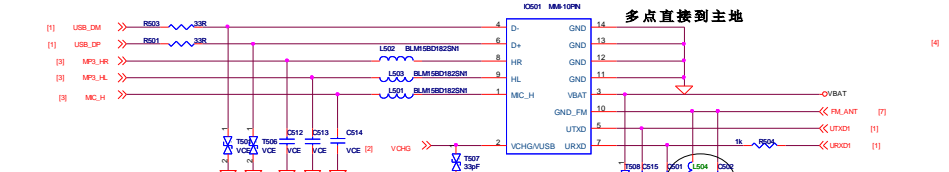


BASEBAND-MCP INTERFACE



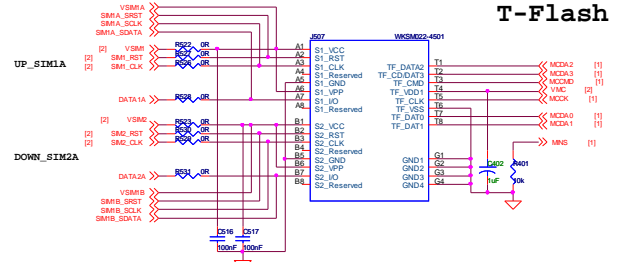


前后摄像头共用焊盘

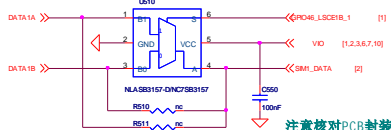
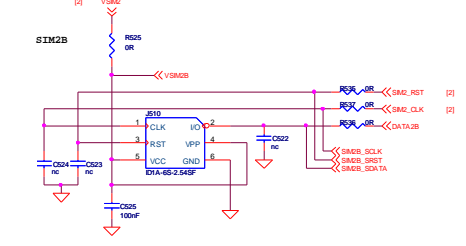
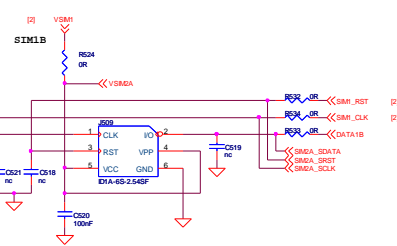


IO_10PIN

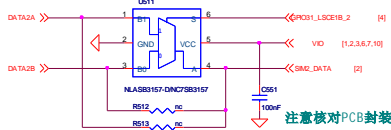
离IO口近, 到IO之间的线加粗



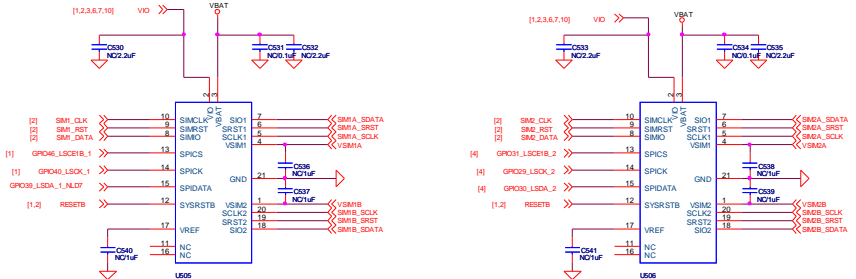
T-Flash



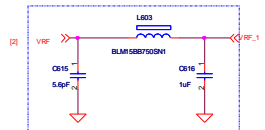
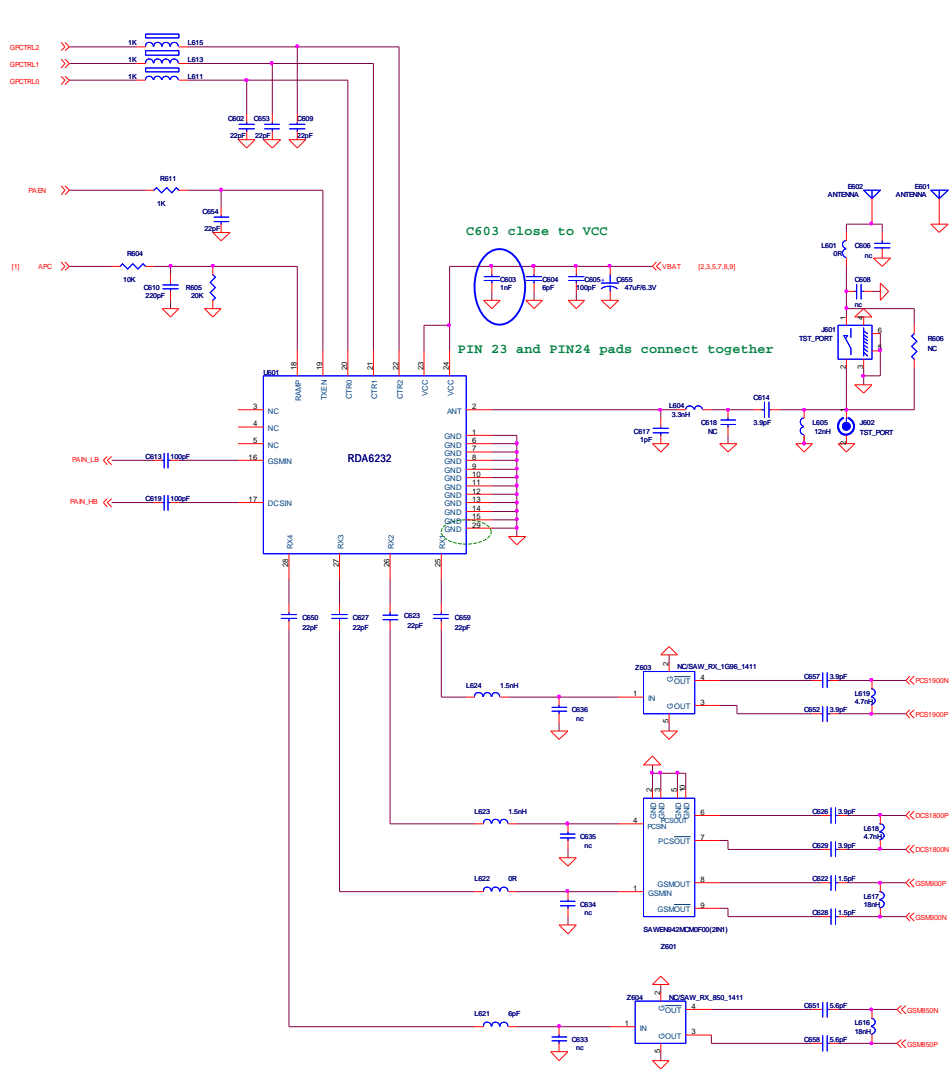
注意核对PCB封装



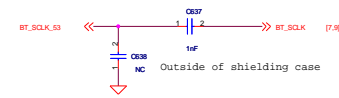
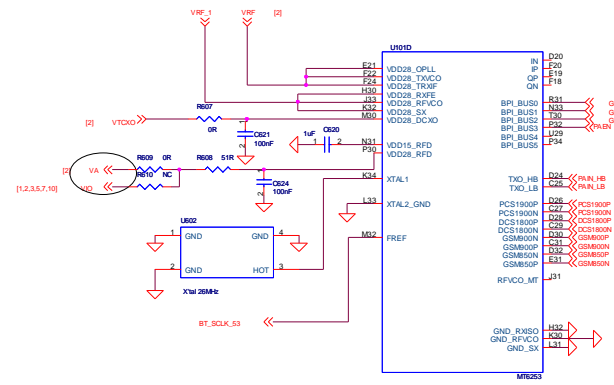
注意核对PCB封装



File	05 SIM, IO, LCM, CAM		Rev	V0.1
Doc A2	Document Number	G01	Sheet	5 of 8
Date:	Wednesday, January 26, 2011		Page	5 of 8

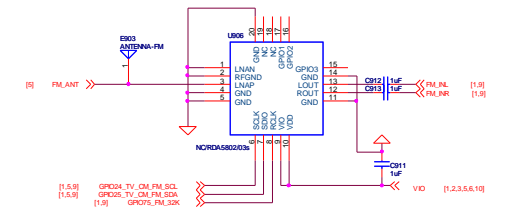
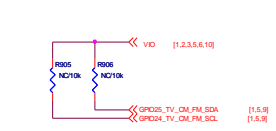
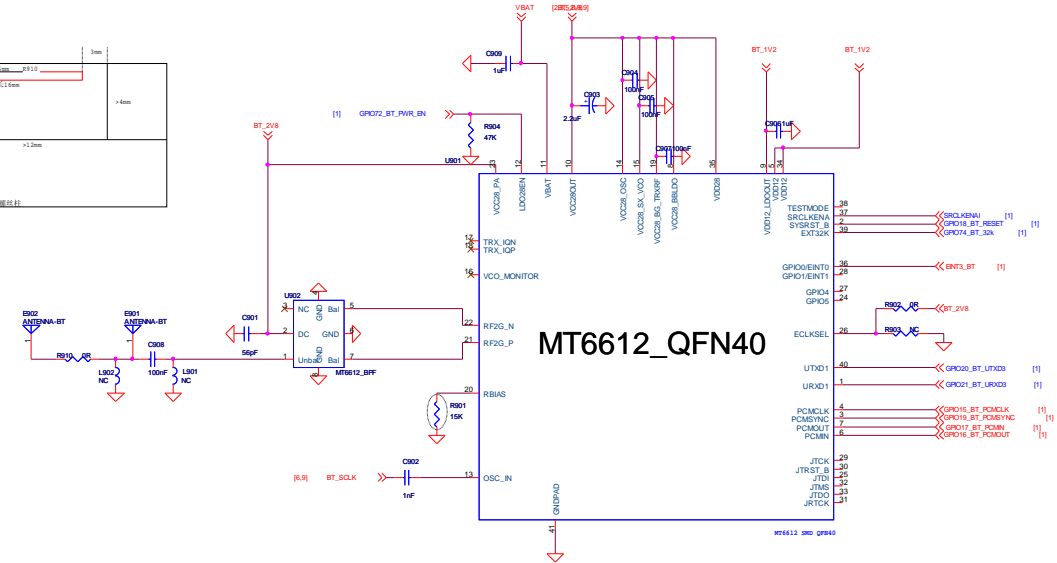
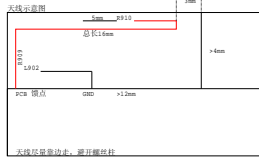


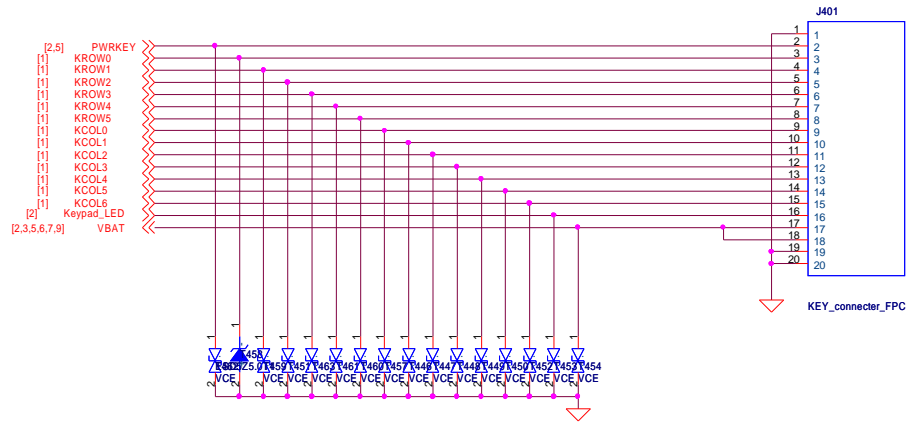
C615 close to VDD28_OPLL
 L603 close to VDD28_OPLL
 C616 close to VDD28_RFVCO



Title		06 2G RF	
Size	A2	Document Number	G01
Date	Thursday, January 27, 2011	Sheet	6 of 8

MT6612





飞梭FPC在主板上的焊盘
在FPC焊盘增加地，防止干扰

Title		
08 KEY CONNECTOR		
Size	Document Number	Rev
A3	G01	V0.1
Date:	Tuesday, January 18, 2011	Sheet 8 of 8

